

customer	
pcb name	
WE article number	
engineer	
date	



Multilayer 8 Layers

PCB Thickness : 2,38 mm +/- 10%

Rigid area Structure	Rigid area Thickness	Material description	Viatypes	Layer usage	Impedance	
					Er	Z[Ohm] Line / Space
Soldermask	15					
L1	45	* Incl. Plating	Top-Layer		3,5	
	230	FR4 TG 150			4,3	
L2	18					
	410	FR4 TG 150			4,8	
L3	18					
	230	FR4 TG 150			4,3	
L4	18					
	410	FR4 TG 150			4,8	
L5	18					
	230	FR4 TG 150			4,3	
L6	18					
	410	FR4 TG 150			4,8	
L7	18					
	230	FR4 TG 150			4,3	
L8	45	* Incl. Plating	Bottom-Layer			
Soldermask	15				3,5	

Notes:
50 % copper occupancy IL
final copper thickness according to IPC 6012
Dielectric material according IPC-4101 E / 128 (127)
For Microvia technology please use our HDI stackups

A.Schilpp/Revision: Created: W. Brylka / Scrutinised: A. Schilpp / Approved: A.Schilpp
Template Revision: 06/2018 by Andreas Schilpp

Via types - Standard and options

